



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Blaine J. Thurgood

**Serial No.:** 10/685,312

**Filed:** October 14, 2003

**For:** INTERPOSER SUBSTRATES WITH  
MULTISEGMENT INTERCONNECT  
SLOTS, SEMICONDUCTOR, DIE  
PACKAGES INCLUDING SAME,  
SEMICONDUCTOR DICE FOR USE  
THEREWITH AND METHODS OF  
FABRICATION

**Confirmation No.:** Unknown

**Examiner:** Unknown

**Group Art Unit:** Unknown

**Attorney Docket No.:** 2269-5520.1US

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 8, 2004  
Date

Signature

Leah J. Barrow  
Name (Type/Print)

**PRELIMINARY AMENDMENT**

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing which begins on page 4 of this paper.

**Remarks** begin on page 7 of this paper.